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**FOR IMMEDIATE RELEASE**

# Press Release

## SEMICON West
## Is Only 2 WEEKS AWAY
## VISIT YINCAE AT BOOTH 6448

(**Albany, NY) 22 June 2016** – The SEMICON West 2016, North America's premier Microelectronics event is less than two weeks away! SEMICON West 2016 will be held at the Moscone Center in San Francisco, CA from July 12th to 14th. We sincerely invite you to stop by our Booth 6448 to learn more about YINCAE Advanced Materials.

YINCAE offers a variety of exclusive Adhesives, Thermal Interface, and Chip/Board/Packaging level materials that have been adopted by leading contract manufacturers and Tier 1 Microelectronic suppliers. Recipient of the 2015 Global Technology Award; YINCAE innovated the **WORLD's FIRST** Lead-Free Solder Joint Encapsulation Adhesive solutions for wafer level, flip chip, POP, LGA, BGA and many more applications. YINCAE offers SJEA for low, medium, and high temperature solder alloy applications for your individualized needs.

YINCAE Advanced Materials, LLC hopes that you are finalizing preparation for the SEMICON WEST 2016. We are looking forward to seeing you in the **North Hall at booth 6448** and will be available to talk about our products and answer any questions that you may have. We hope that you will join us at the conference to learn about YINCAE and the products that we have to offer. We develop exclusive products that no other company can provide. We look forward to seeing you at booth 6448!

If you wish to visit the official website of YINCAE Advanced Materials, LLC, please visit us by clicking the following link: YINCAE Website.

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Founded in 2005 & headquartered in Albany, New York, YINCAE Advanced Materials is a leading manufacturer and supplier of high-performance coatings, adhesives and electronic materials used in the microchip & optoelectronic devices. YINCAE products provide new technologies to support manufacturing processes from wafer level, to package level, to board level and final devices while facilitating smarter and faster production and supporting green initiatives.

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